

# MSK19N03

## N-Channel 30-V (D-S) MOSFET

### Description

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low RDS(on) and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, and PCMCIA cards, cellular and cordless telephones.

### Features

- Low rDS(on) provides higher efficiency and extends battery life
- Low thermal impedance copper lead frame DFN3x3 saves board space
- Fast switching speed
- High performance trench technology
- RoHS compliant package

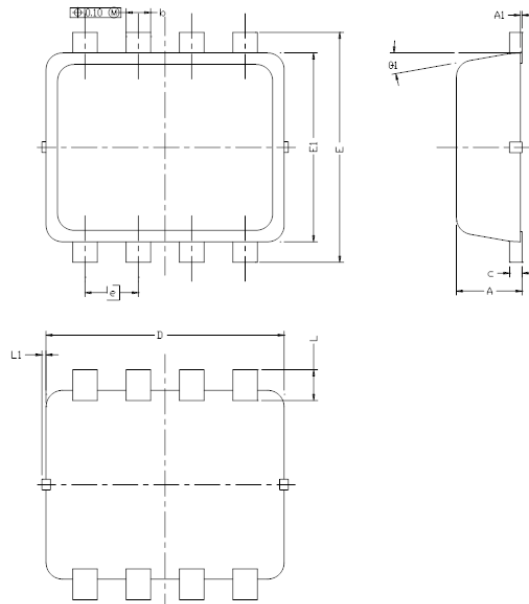
**Package type :** DFN 3X3

### Packing & Order Information

3,000/Reel

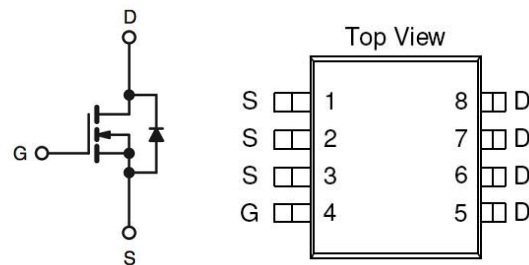


**RoHS  
COMPLIANT**



DIM.	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.700	0.800	0.900	0.028	0.0315	0.0354
A1	0.000	-	0.050	0.000	-	0.002
b	0.240	0.300	0.350	0.009	0.012	0.014
c	0.080	0.152	0.250	0.003	0.006	0.010
DIM.	2.90 BSC			0.114 BSC		
E	2.80 BSC			0.110 BSC		
E1	2.30 BSC			0.091 BSC		
e	0.65 BSC			0.026 BSC		
L	0.200	0.375	0.450	0.008	0.0148	0.0177
L1	0.000	-	0.100	0.000	-	0.004
θ1	0.000	10.000	12.000	0.000	10.000	12.000

### Graphic symbol



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (T<sub>A</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current -Continuous <sup>a</sup> (T <sub>A</sub> =25°C)	±19	A
	Drain Current -Continuous <sup>a</sup> (T <sub>A</sub> =70°C)	±16	A
I <sub>DM</sub>	Pulsed Drain Current <sup>b</sup>	±40	A
P <sub>D</sub>	Total Power Dissipation <sup>a</sup> (T <sub>A</sub> =25°C)	3.5	W
	Total Power Dissipation <sup>a</sup> (T <sub>A</sub> =70°C)	2	W

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#### Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Value	Unit
$I_S$	Continuous Source Current (Diode Conduction) <sup>a</sup>	2	A
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$

#### Thermal Data

Symbol	Parameter	Max.	Units
$R_{\theta JC}$	Maximum Junction-to-Case <sup>a</sup> ( $t \leq 5$ sec)	35	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Maximum Junction-to-Ambient <sup>a</sup> ( $t \leq 5$ sec)	50	

Note:

1. Surface Mounted on 1"x1" FR4 Board.
2. Pulse width limited by maximum junction temperature.

#### Static

Symbol	Test Conditions	Min	Typ.	Max.	Units
$V_{SD}$	$V_{GS} = 0$ V, $I_S = 2.3$ A	--	0.7	--	V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\mu\text{A}$	1	--	3	V
$I_{DSS}$	$V_{DS} = 24$ V, $V_{GS} = 0$ V $V_{DS} = 24$ V, $V_{GS} = 0$ V, $T_J = 55^{\circ}\text{C}$	--	--	1 25	$\mu\text{A}$
$I_{GSS}$	$V_{GS} = 20$ V, $V_{DS} = 0$	--	--	$\pm 100$	nA
$I_{D(ON)}$	$V_{DS} = 5$ V, $V_{GS} = 10$ V	20	--	--	A
$R_{DS(ON)}$	$V_{GS} = 10$ V, $I_D = 10$ A $V_{GS} = 4.5$ V, $I_D = 8$ A	--	--	6.9 9.8	$\text{m}\Omega$
$G_{FS} * I$	$V_{DS} = 15$ V, $I_D = 10$ A		40		S

#### Dynamic Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
$C_{ISS}$	Input Capacitance	$V_{DS} = 15$ V, $V_{GS} = 0$ V, $f = 1.0\text{MHz}$	--	1302	--	pF
$C_{OSS}$	Output Capacitance		--	423	--	pF
$C_{RSS}$	Reverse Transfer Capacitance		--	171	--	pF
$Q_g$	Total Gate Charge	$V_{DS} = 15$ V, $I_D = 10$ A, $V_{GS} = 4.5$ V	--	11	--	nC
$Q_{gs}$	Gate-Source Charge		--	6	--	nC
$Q_{gd}$	Gate-Drain Charge		--	4	--	nC
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 25$ V, $I_D = 1$ A, $R_L = 25$ $\Omega$ , $V_{GEN} = 10$ V	--	10	--	ns
$t_r$	Rise Time		--	5	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	22	--	ns
$t_f$	Fall Time		--	4	--	ns

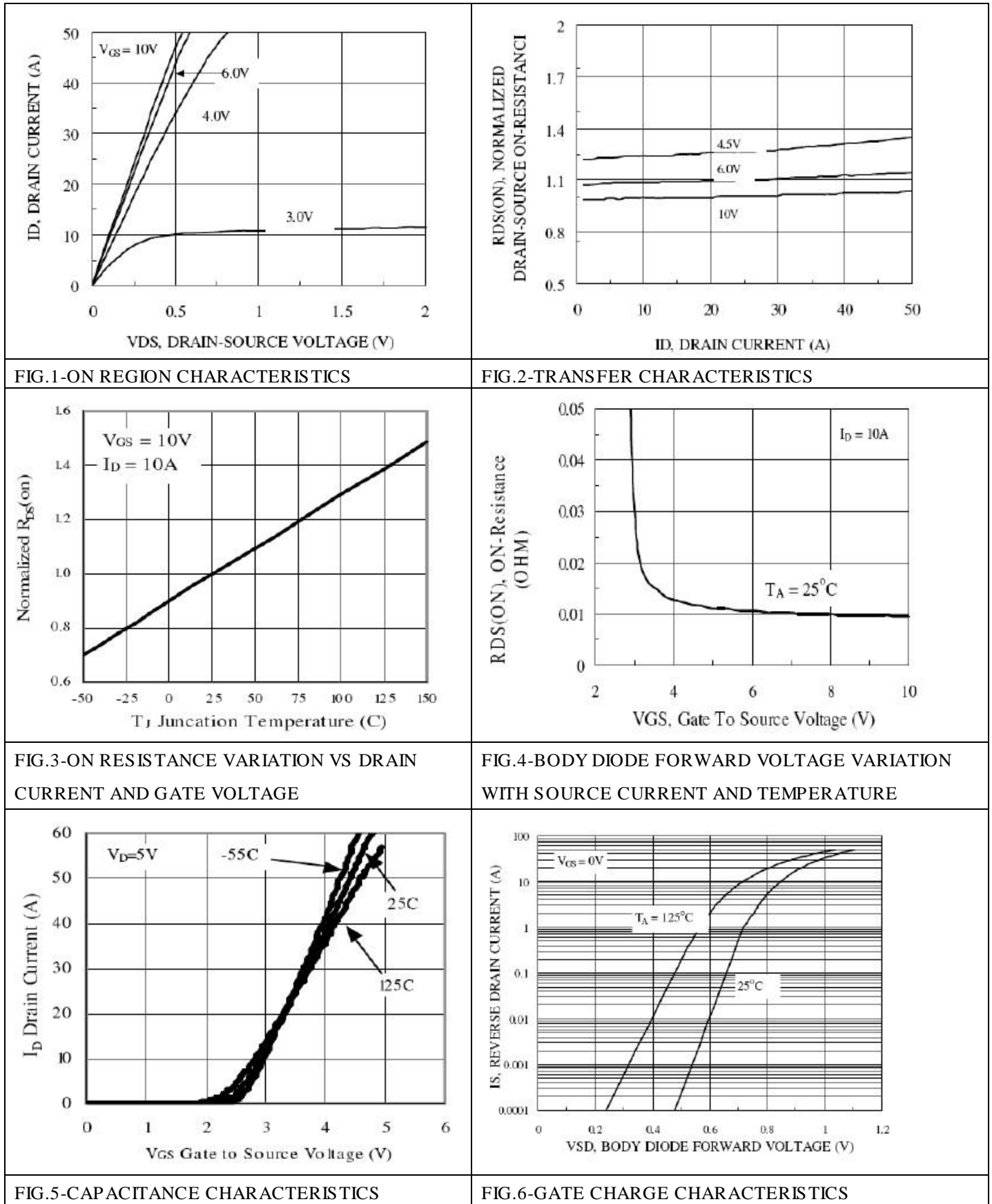
Notes

- a. Pulse test:  $PW \leq 300\mu\text{s}$  duty cycle  $\leq 2\%$ .
- b. Guaranteed by design, not subject to production testing.

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#### ■ Characteristics Curve



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#### ■ Characteristics Curve

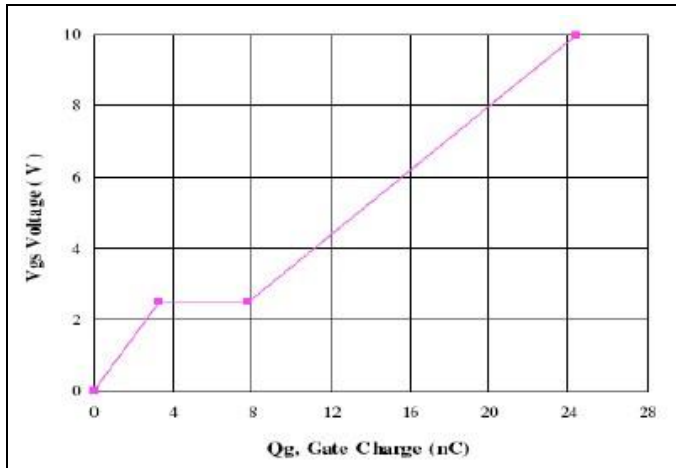


FIG.7-BREAKDOWN VOLTAGE VARIATION VS TEMPERATURE

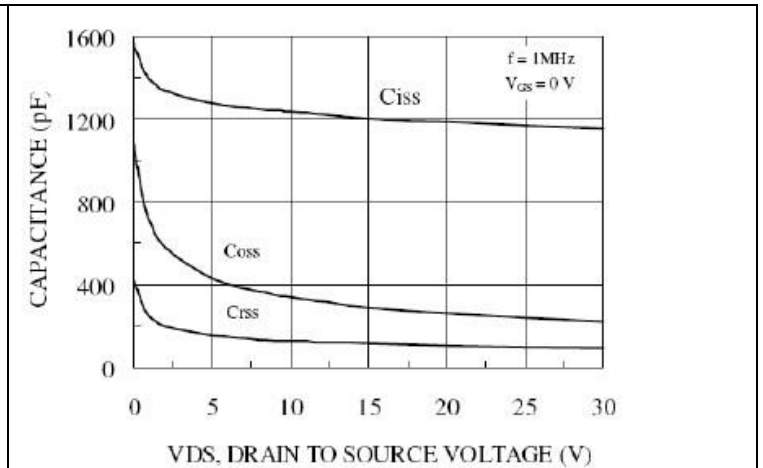


FIG.8-ON-RESISTANCE VARIATION VS TEMPERATURE

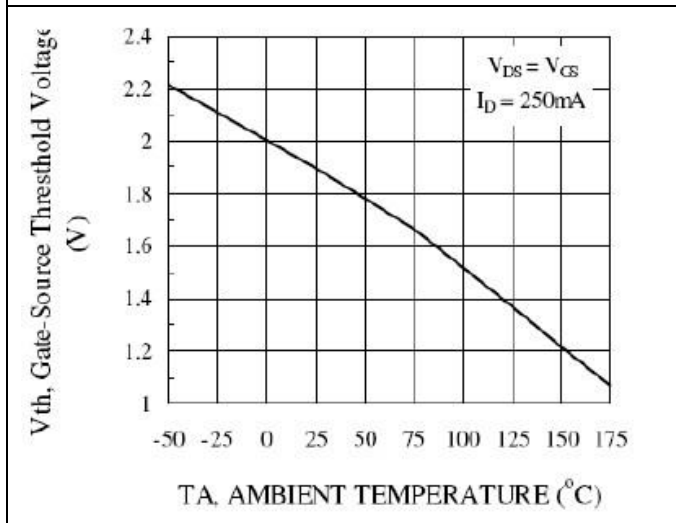


FIG.9-MAXIMUM SAFE OPERATING AREA

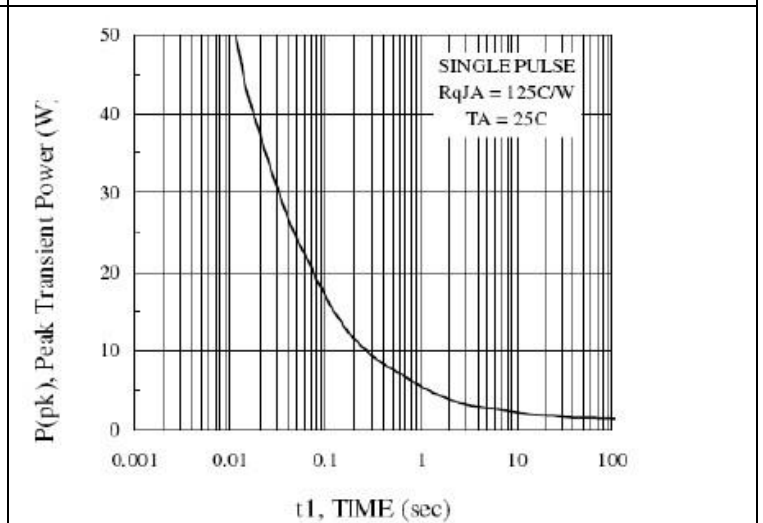


FIG.10-MAXIMUM DRAIN CURRENT VS CASE TEMPERATURE

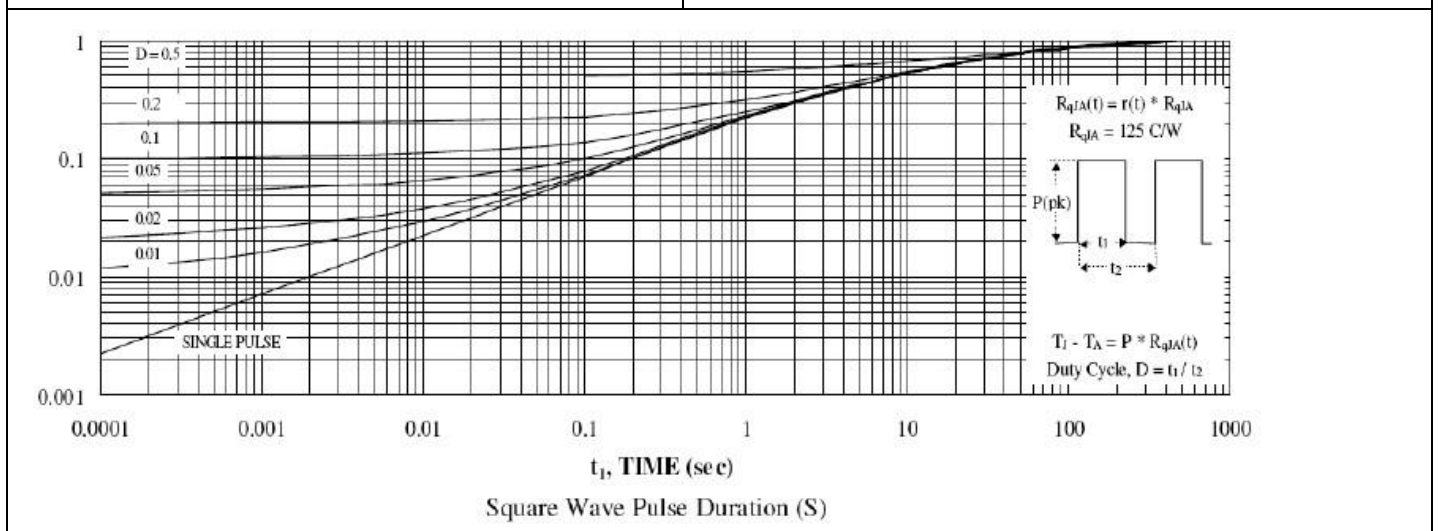


FIG.11-TRANSIENT THERMAL RESPONSE CURVE

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